

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Dongchul Lee	03/08/2012
RECEIVING PARTY DATA	
Name:	BOSTON SCIENTIFIC NEUROMODULATION CORPORATION
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13420258
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ATTORNEY DOCKET NUMBER:	10-00165US01
NAME OF SUBMITTER:	Michael J. Bolan
Total Attachments: 2 source=Signed Assignment#page1.tif source=Signed Assignment#page2.tif	

OP \$40.00 13420258

ASSIGNMENT OF PATENT APPLICATION

WHEREAS, I, Dongchul Lee, a citizen of Republic of Korea (hereinafter referred to as "ASSIGNOR"), have invented a certain invention entitled **NEUROSTIMULATION SYSTEM FOR DEFINING IDEAL MULTIPOLE CONFIGURATIONS AT LEAD BOUNDARY** (Attorney Docket No. 10-00165US01) for which a United States Patent Application is being filed. This Application also claims priority to U.S. Provisional Patent Application Number 61/453,015 filed with the U.S. Patent and Trademark Office on March 15, 2011; and

WHEREAS, **BOSTON SCIENTIFIC NEUROMODULATION CORPORATION**, a corporation organized and existing under and by virtue of the laws of the state of Delaware and having its principal place of business at 25155 Rye Canyon Loop, Valencia, CA 91355 (hereinafter referred to as "ASSIGNEE"), is desirous of acquiring the exclusive right, title and interest in, to and under said invention and in, to and under any Patent or similar legal protection to be obtained therefor in the United States of America, its territorial possessions and in any and all countries foreign thereto.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR hereby sells, assigns, transfers and sets over unto the said ASSIGNEE, its successors and assign, the full and exclusive right, title and interest to said invention and to all Letters Patent and applications therefore, or similar legal protection, not only in the United States and its territorial possessions, but in all countries foreign thereto to be obtained for said invention by said application, and to any continuation, division, renewal, substitute or reissue thereof or any legal equivalent thereof in the United States or a foreign country for the full term or terms for which the same may be granted, including all priority rights under the International Convention; and

ASSIGNOR hereby authorizes and requests the United States Commissioner of Patents and Trademarks, and any officials of foreign countries whose duty it is to issue patents or any legal equivalent thereof, to issue said patents to ASSIGNEE, its successors and assigns, in accordance with this Assignment.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Agreement;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents in the United States or in any foreign country, which may be necessary or desirable to carry out the purposes thereof.

08 Mar 2012  
Date

  
Dongchul Lee